

In the Claims

The claims have been amended as follows.

- 1 1. (previously presented) A method for assembling an electronic module
2 comprising:
3 attaching a chip to a substrate using a first solder interconnection array;
4 attaching a board to said substrate using a second solder interconnection array
5 such that a space is defined between said board and said substrate having a
6 gap height ranging from about 300 microns to about 900 microns, said
7 second solder interconnection array residing entirely within said space; and
8 providing an underfill material within said space prior to applying compressive
9 forces to said electronic module, said underfill material having a filler
10 material with a particle size ranging from about 32 microns to about 300
11 microns present in an amount ranging from about 60 to 64 weight percent,
12 said underfill material being in direct contact with said board and said
13 substrate to maintain said space and optimize integrity of said second solder
14 interconnection array during application of said compressive forces.
- 1 2. (previously presented) The method of claim 1 further including providing a
2 mechanical support structure comprising at least one rigid metallic ball within said
3 space.

1 3. (previously presented) The method of claim 1 further including providing a
2 mechanical support structure comprising a bracket within said space.

1 4. (previously presented) The method of claim 1 further including providing a
2 mechanical support structure comprising a frame within said space.

1 5. (previously presented) A method for assembling an electronic module
2 comprising:

3 attaching a chip to a substrate using a first solder interconnection array;

4 attaching an organic board to said substrate using a second solder
5 interconnection array thereby defining a space between said organic board
6 and said substrate, said second solder interconnection array residing entirely
7 within said space;

8 depositing an underfill material at discrete locations within said space such that
9 said underfill material contacts both said organic board and said substrate
10 and selected solder joints of said second solder interconnection array for
11 partially encapsulating said second solder interconnection array at said
12 discrete locations; and

13 curing said underfill material to form a rigid matrix within said space to maintain
14 and enhance integrity of said second solder interconnection array.

1 6. (previously presented) The method of claim 5 further including the steps of
2 cleaning surfaces of said organic board and said substrate within said space and

3 heating said organic board followed by depositing said underfill material to increase
4 wetting characteristics of said underfill material and enhance adhesion of said
5 underfill material to said organic board and said substrate.

1 7. (original) The method of claim 5 further including the step of providing at
2 least one rigid metallic ball within said space to further maintain and enhance
3 integrity of said second solder interconnection array.

1 8. (original) The method of claim 5 further including the step of providing at
2 least one mechanical support structure selected from the group consisting of a
3 bracket, a frame and a collar within said space to further maintain and enhance
4 integrity of said second solder interconnection array.

1 9. (original) The method of claim 5 wherein said second solder
2 interconnection array comprises a single melt solder interconnection array.

1 10. (original) The method of claim 5 wherein said second solder
2 interconnection array comprises a dual melt solder interconnection array.

1 11. (canceled)

1 12. (canceled)

1 13. (original) The method of claim 5 wherein said space has gap heights
2 residing between said organic board and said substrate ranging from about 300
3 microns to about 900 microns, said underfill material being capable of filling said
4 gap heights.

1 14. (previously presented) The method of claim 13 wherein said underfill
2 material in its uncured state comprises a polymeric material having a filler material
3 present in an amount ranging from about 60% by weight per solution to about 64%
4 by weight per solution, said filler material having a particle size ranging from about
5 32 microns to about 300 microns in diameter.

1 15. (original) The method of claim 14 wherein said underfill material in its
2 uncured state has a density ranging from about 1.5 g/cc to about 2.0 g/cc, a
3 viscosity at 25°C greater than about 5,000 cP, and a Thixotropic Index ranging from
4 about 1.0 to about 2.0.

1 16. (original) The method of claim 15 wherein said underfill material in its cured
2 state has a glass transition temperature ranging from about 135°C to about 145°C,
3 and a dynamic tensile modulus strength at about 25°C greater than about 5 Gpa.

1 17. (original) The method of claim 16 wherein said substrate comprises a
2 ceramic substrate, said cured underfill material has a CTE below Tg of about 18
3 ppm/°C to about 21 ppm/°C, and a CTE above the Tg of about 85 ppm/°C.

1 18. (original) The method of claim 16 wherein said substrate comprises a organic
2 substrate, said cured underfill material has a CTE below T_g of about 12 ppm/°C to
3 about 25 ppm/°C, and a CTE above the T_g of about 70 ppm/°C.

1 19. (previously presented) An electronic module assembly comprising:
2 a chip attached to a substrate via a first solder interconnection array;
3 a board attached to said substrate via a second solder interconnection array;
4 a space defined between said organic board and said substrate having a gap
5 height ranging from about 300 microns to about 900 microns, said second
6 solder interconnection array residing entirely within said space; and
7 a rigid matrix of underfill material within said space being in direct contact with
8 said board and said substrate for encapsulating said second solder
9 interconnection array to maintain said space and optimize integrity of said
10 second solder interconnection array, said underfill material having a filler
11 material with a particle size ranging from about 32 microns to about 300
12 microns present in an amount ranging from about 60 to about 64 weight
13 percent.

1 20. (previously presented) The assembly of claim 19 further including a creep
2 resistant structure selected from the group consisting of a metallic ball, a bracket, a
3 frame, a collar, and combinations thereof.

1 21. (previously presented) The method of claim 1 wherein said underfill
2 material partially encapsulates said second solder interconnection array at discrete
3 locations.

1 22. (previously presented) The assembly of claim 19 wherein said underfill
2 material partially encapsulates said second solder interconnection array at discrete
3 locations.